

**Amendments to the Specification**

Please replace the paragraph beginning at line 14 of page 13 with the following rewritten paragraph:

With reference to FIG. 9, if provided, a heat stamping device 500 applies heat and pressure to the inner layer 188, thereby compressing the inner layer 188 between the heat stamping device 500 and the access panel assembly heat bondable layer 206. The compression forces and heat serve to bond the inner layer 188 to the heat bondable layer 206 at a bonded line 314. The bond line 314 may have a frangible portion 502 associated therewith. This frangible portion 502 serves to allow access to the container interior 102, in a manner that will be described later herein. Exemplary ways to attach an inner layer to an opening panel are disclosed, for example, in U.S. patent application S/N \_\_\_\_\_ of Ser. No. 10/027,744 of Joseph C. Walsh titled CARTON BLANK AND CARTON FORMED THEREFROM filed on Dec. 20, 2001 (~~attorney docket No. PP-5.71(c)~~), which is hereby specifically incorporated by reference for all that is disclosed therein. Utilization of a heat stamping device is considered to be an exemplary manufacturing process, and other methods for frangibly attaching the inner layer 188 to the access panel assembly 200 have been contemplated; a few of these alternative embodiments will be described later herein (e.g. FIG. 21).